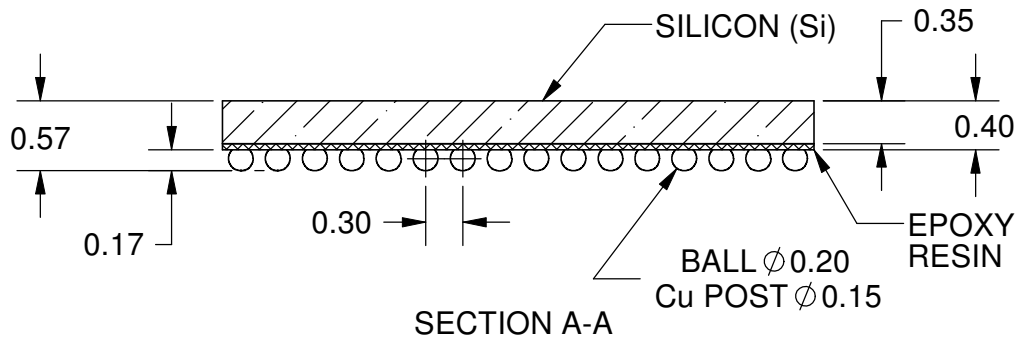
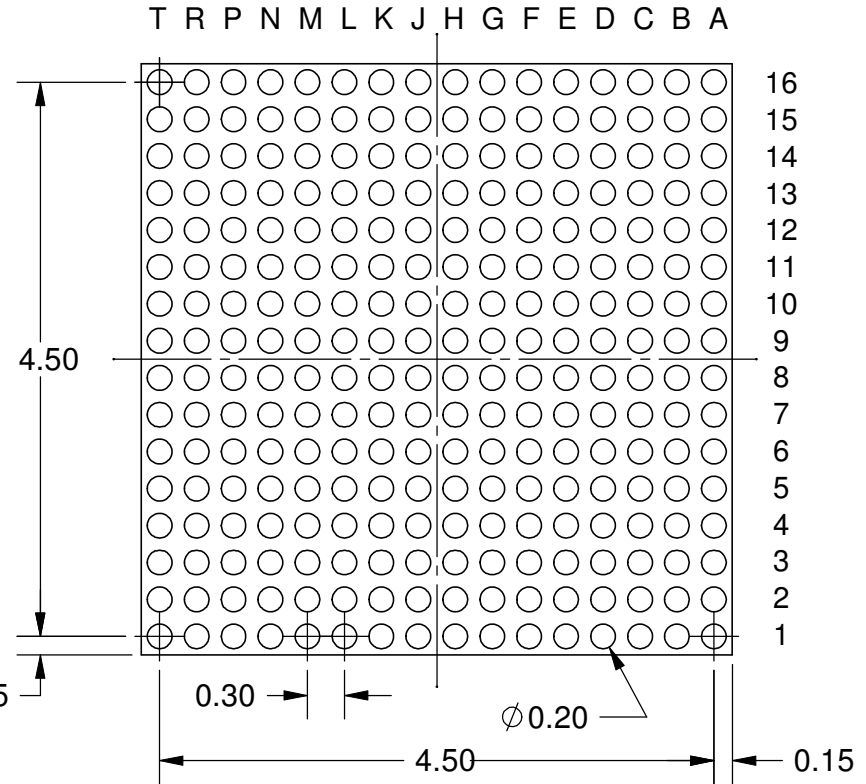
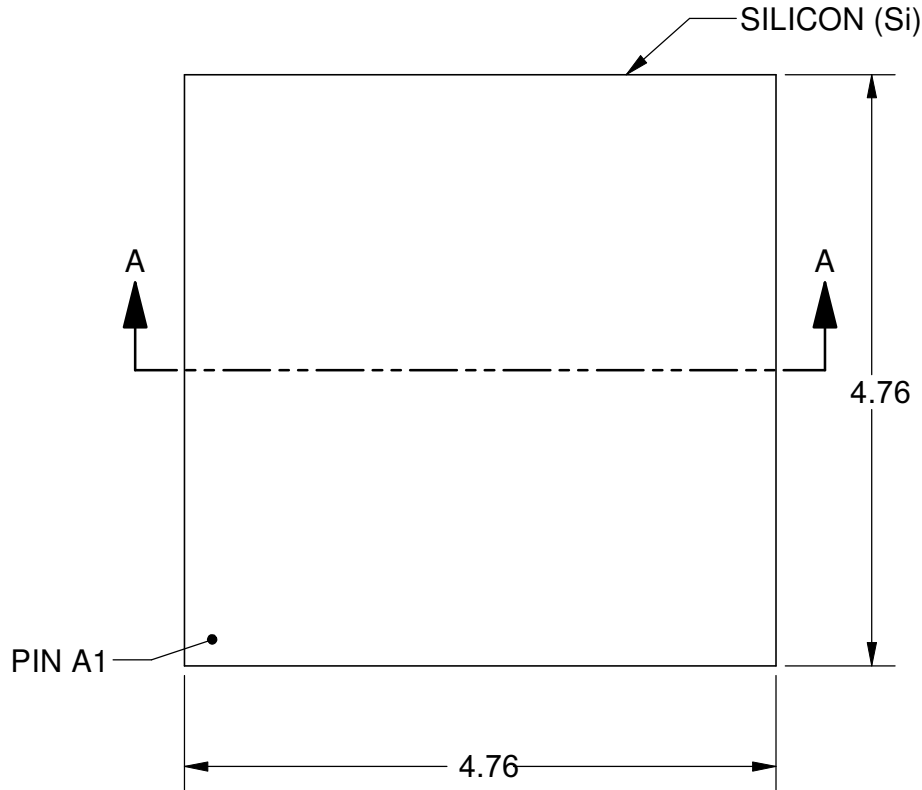


TOP VIEW

BALL VIEW



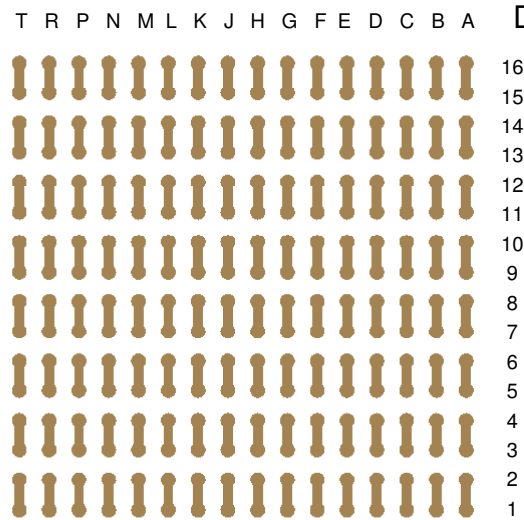
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY:
STANDARD: SAC305 (Sn96.5/Ag3.0/Cu0.5).
- 3) BALL DIAMETER (BEFORE REFLOW): 0.25mm.
- 4) NON-SOLDER MASK DEFINED PAD.
- 5) PAD Cu DIAMETER: 0.20mm.
- 6) SUBSTRATE MATERIAL: Si (SILICON).
- 7) DAISY CHAIN PATTERN (SEE PAGE 2).

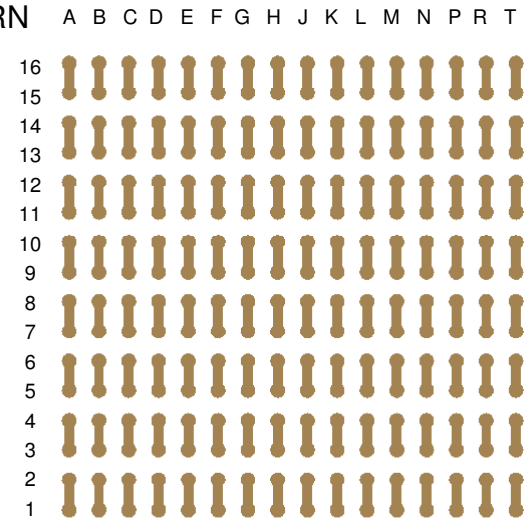
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
WLP256T.3C-DC168D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES

TOLERANCE UNLESS NOTED		APPROVALS	DATE	TopLine [®]			
X.X	+/- 0.1						
X.XX	+/- 0.03	DRAWN J. Hines	12/28/2010	TITLE WLP256T.3C-DC168D			
X.XXX	+/- 0.003			256-BALL P=0.3mm (TEG0306)			
ANGLES	+/- 0.5°	ENG		SCALE 16.75:1			
ALL DIMENSIONS IN		MFG		SIZE A		DRAWING NO. 531682	
<input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		QA		REV A		REV A	
THIRD ANGLE PROJECTION		CUST		DO NOT SCALE DRAWING			
		REVISED		SHEET 1 OF 2			

BALL VIEW

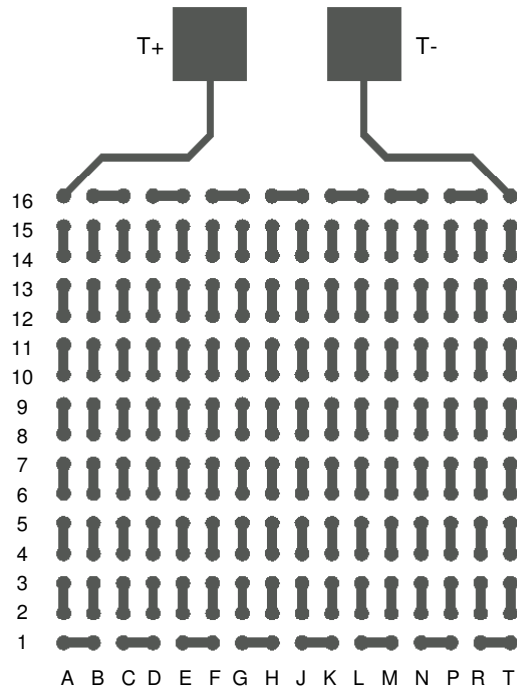


DAISY CHAIN PATTERN

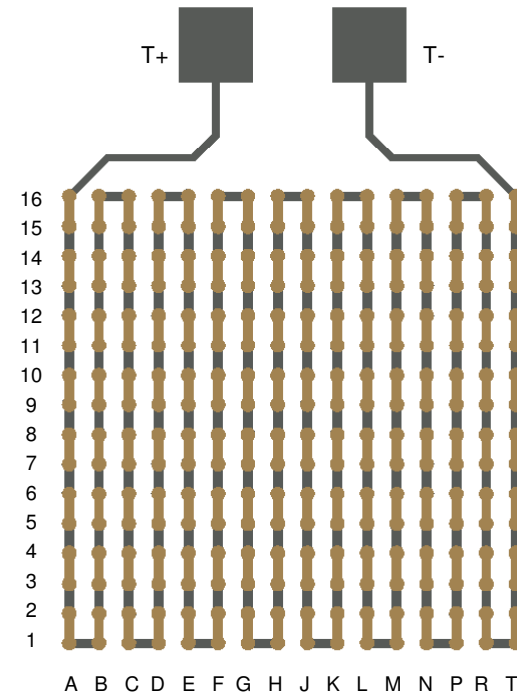


BOTTOM SIDE
(TOP X-RAY VIEW)

TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



TEST VEHICLE BOARD

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.15mm (5.9mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.10mm (3.9mil).

TopLine[®]

TITLE			
WLP256T.3C-DC168D			
256-BALL P=0.3mm (TEG0306)			
SCALE	SIZE	DRAWING NO.	REV
13.5:1	A	531682	A
DO NOT SCALE DRAWING			SHEET 2 OF 2